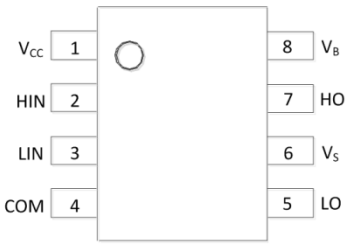
Pin Diagrams

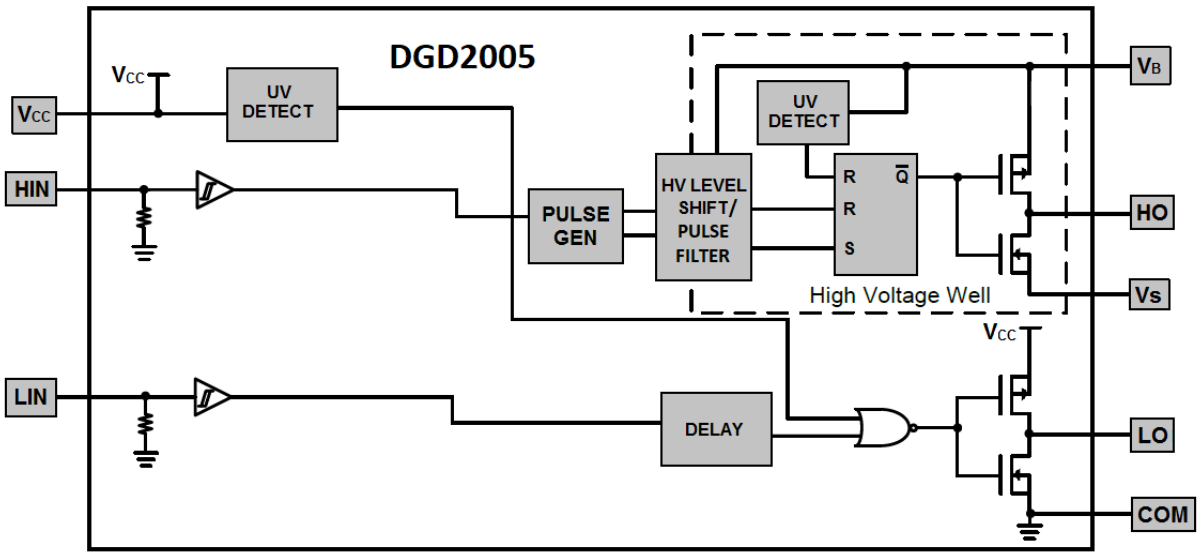


Top View: SO-8

Pin Descriptions

Pin Number	Pin Name	Function
1	V_{CC}	Low-Side and Logic Fixed Supply
2	HIN	Logic Input for High-Side Gate Driver Output, in Phase with HO
3	LIN	Logic Input for Low-Side Gate Driver Output, in Phase with LO
4	COM	Low-Side Return
5	LO	Low-Side Gate Drive Output
6	V_S	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	V_B	High-Side Floating Supply

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V_B	-0.3 to +224	V
High-Side Floating Supply Offset Voltage	V_S	V_B-24 to V_B+0.3	V
High-Side Floating Output Voltage	V_{HO}	V_S-0.3 to V_B+0.3	V
Offset Supply Voltage Transient	dV_S / dt	50	V/ns
Low-Side and Logic Fixed Supply Voltage	V_{CC}	-0.3 to +24	V
Low-Side Output Voltage	V_{LO}	-0.3 to V_{CC}+0.3	V
Logic Input Voltage (HIN and LIN)	V_{IN}	-0.3 to V_{CC}+0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P_D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\Theta JA}$	200	°C/W
Operating Temperature	T_J	+150	°C
Lead Temperature (Soldering, 10s)	T_L	+300	
Storage Temperature Range	T_{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V_B	V_S + 10	V_S + 20	V
High Side Floating Supply Offset Voltage	V_S	(Note 6)	200	V
High Side Floating Output Voltage	V_{HO}	V_S	V_B	V
Low Side and Logic Fixed Supply Voltage	V_{CC}	10	20	V
Low Side Output Voltage	V_{LO}	0	V_{CC}	V
Logic Input Voltage	V_{IN}	0	5	V
Ambient Temperature	T_A	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +200V.

DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic “1” Input Voltage	V_{IH}	2.5	—	—	V	—
Logic “0” Input Voltage	V_{IL}	—	—	0.6	V	—
High Level Output Voltage, V_{BIAS} - V_O	V_{OH}	—	0.05	0.2	V	I_O = 2mA
Low Level Output Voltage, V_O	V_{OL}	—	0.02	0.1	V	I_O = 2mA
Offset Supply Leakage Current	I_{LK}	—	—	50	µA	V_B = V_S = 200V
Quiescent V_{BS} Supply Current	I_{BSQ}	20	75	130	µA	V_{IN} = 0V or 5V
Quiescent V_{CC} Supply Current	I_{CCQ}	60	120	180	µA	V_{IN} = 0V or 5V
Logic “1” Input Bias Current	I_{IN+}	—	5.0	20	µA	V_{IN} = 5V
Logic “0” Input Bias Current	I_{IN-}	—	—	2.0	µA	V_{IN} = 0V
V_{BS} Supply Undervoltage Positive Going Threshold	V_{BSUV+}	8.0	8.9	9.8	V	—
V_{BS} Supply Undervoltage Negative Going Threshold	V_{BSUV-}	7.4	8.2	9.0	V	—
V_{CC} Supply Undervoltage Positive Going Threshold	V_{CCUV+}	8.0	8.9	9.8	V	—
V_{CC} Supply Undervoltage Negative Going Threshold	V_{CCUV-}	7.4	8.2	9.0	V	—
Undervoltage Lockout Hysterisis	V_{UVLOH}	0.3	0.7	—	V	—
Output High Short Circuit Pulsed Current	I_{O+}	130	290	—	mA	V_O = 0V, V_{IN} = Logic “1”, PW ⩽ 10µs
Output Low Short Circuit Pulsed Current	I_{O-}	270	600	—	mA	V_O = 15V, V_{IN} = Logic “0”, PW ⩽ 10µs

Note: 7. The V_{IN} and I_{IN} parameters are referenced to COM and are applicable to the two logic pins: HIN and LIN. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-On Propagation Delay	t_{ON}	—	100	300	ns	V_S = 0V
Turn-Off Propagation Delay	t_{OFF}	—	100	280	ns	V_S = 0V or 200V
Delay Matching	t_{DM}	—	—	30	ns	—
Turn-On Rise Time	t_R	—	90	220	ns	V_S = 0V
Turn-Off Fall Time	t_F	—	30	80	ns	V_S = 0V

Timing Waveforms

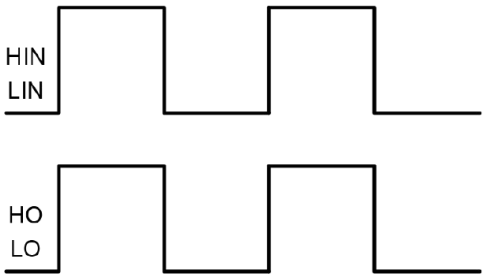


Figure 1. Input / Output Timing Diagram

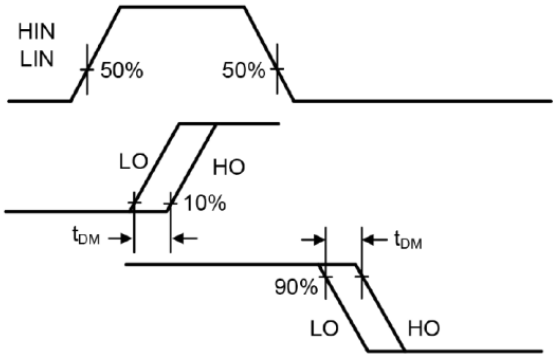


Figure 2. Delay Matching Waveform Definitions

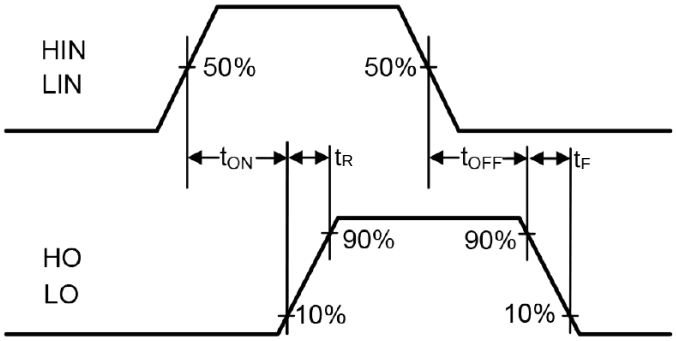


Figure 3. Switching Time Waveform Definitions

Typical Performance Characteristics (V_{CC} = 15V, @T_A = +25°C, unless otherwise specified.)

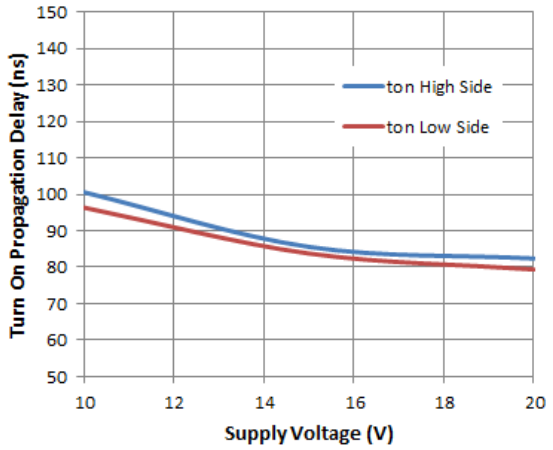


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

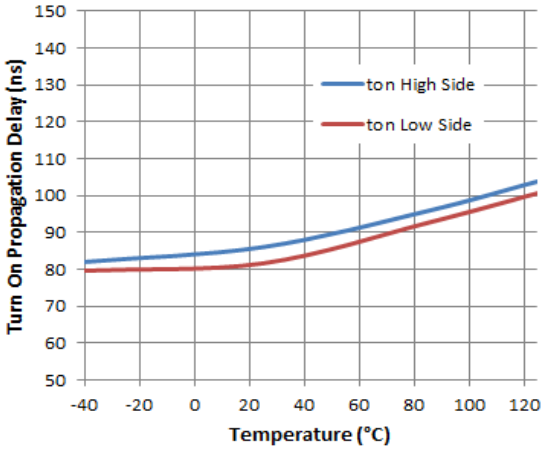


Figure 5. Turn-on Propagation Delay vs. Temperature

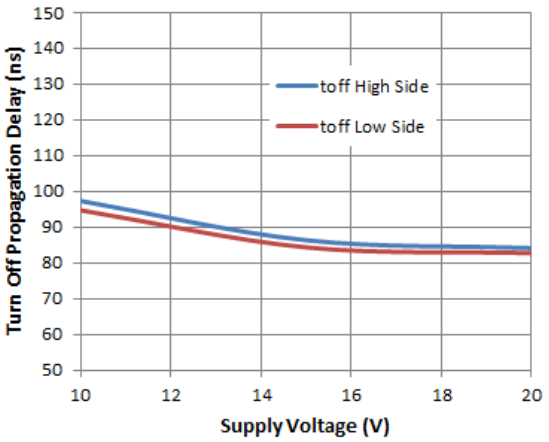


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

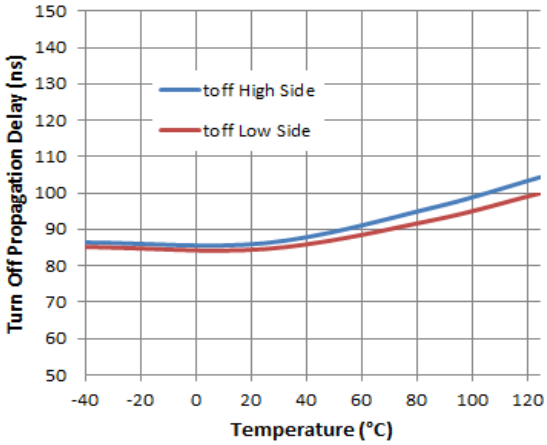


Figure 7. Turn-off Propagation Delay vs. Temperature

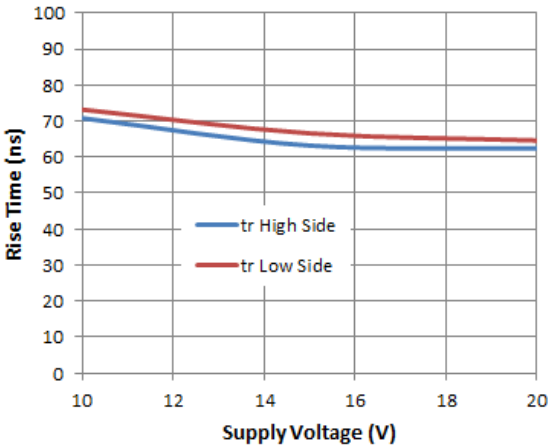


Figure 8. Rise Time vs. Supply Voltage

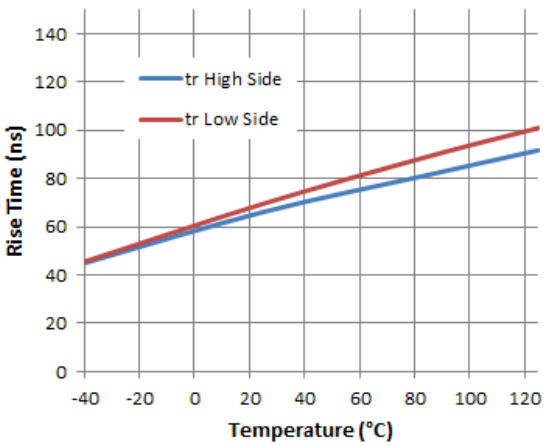


Figure 9. Rise Time vs. Temperature

Typical Performance Characteristics (continued)

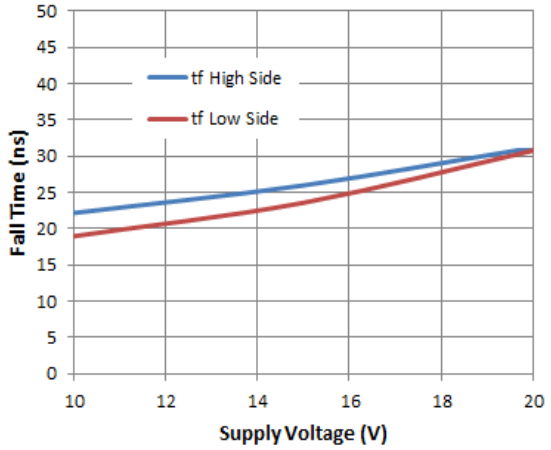


Figure 10. Fall Time vs. Supply Voltage

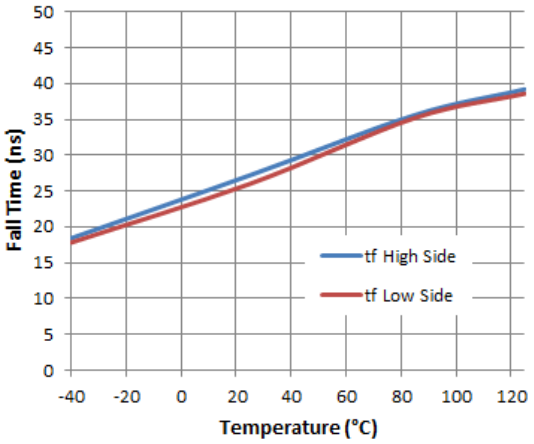


Figure 11. Fall Time vs. Temperature

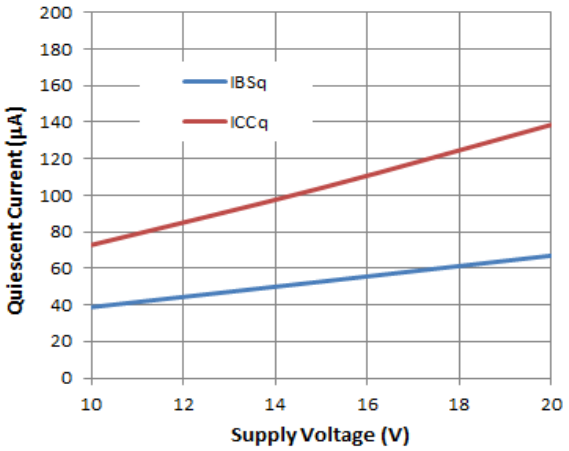


Figure 12. Quiescent Current vs. Supply Voltage

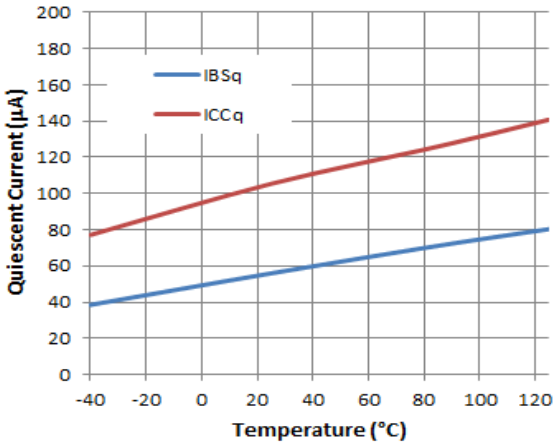


Figure 13. Quiescent Current vs. Temperature

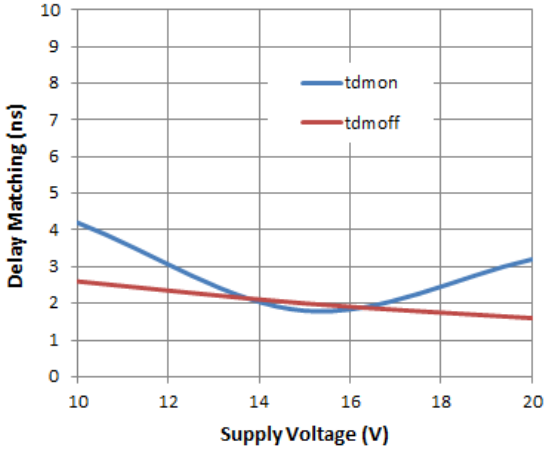


Figure 14. Delay Matching vs. Supply Voltage

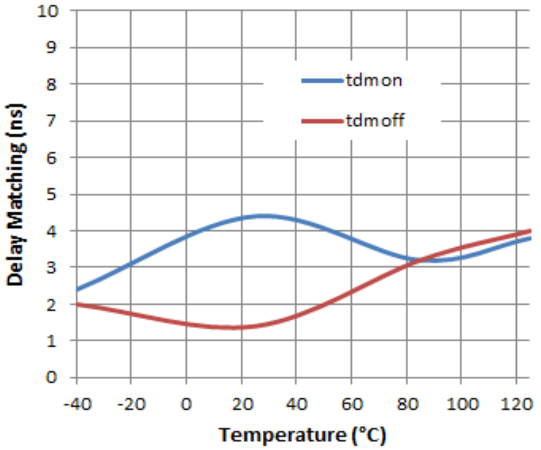


Figure 15. Delay Matching vs. Temperature

Typical Performance Characteristics (continued)

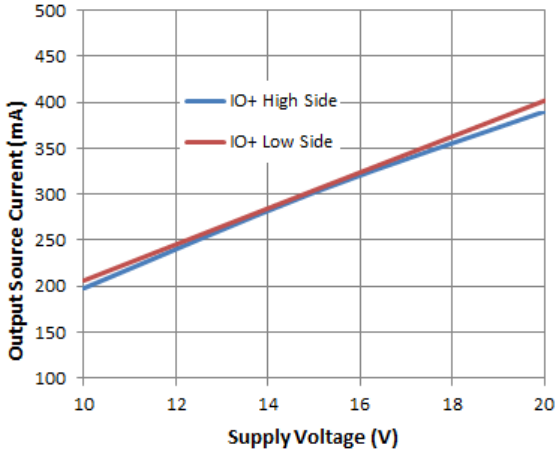


Figure 16. Output Source Current vs. Supply Voltage

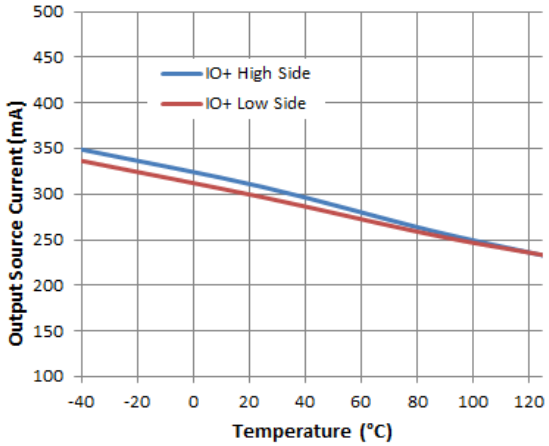


Figure 17. Output Source Current vs. Temperature

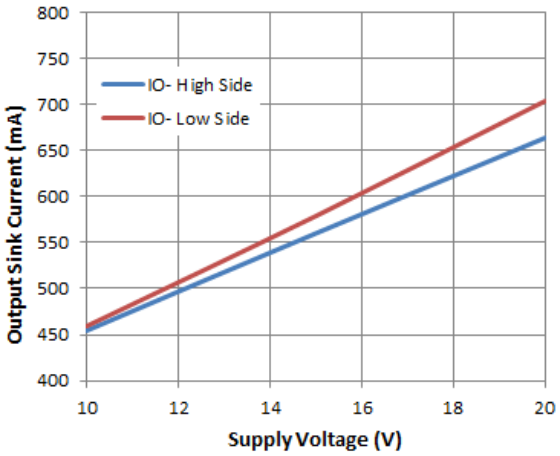


Figure 18. Output Sink Current vs. Supply Voltage

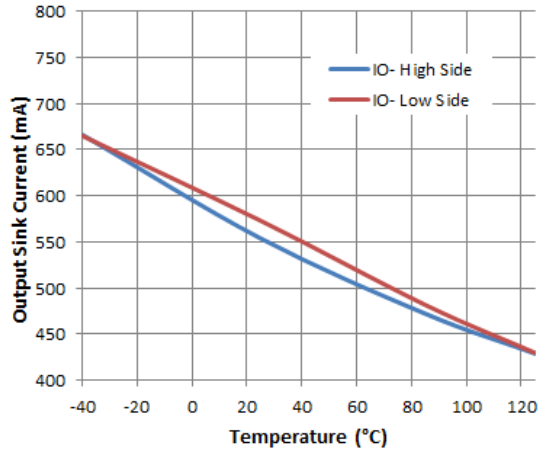


Figure 19. Output Sink Current vs. Temperature

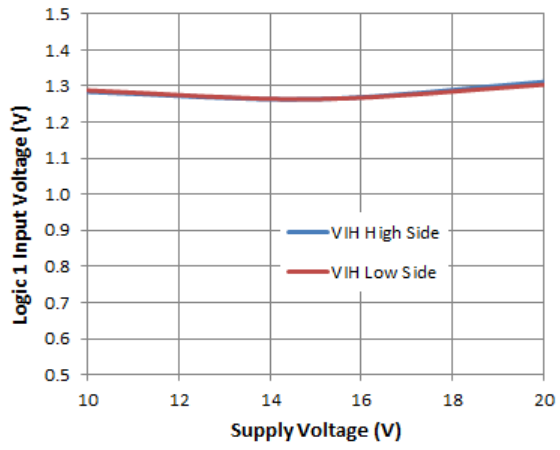


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

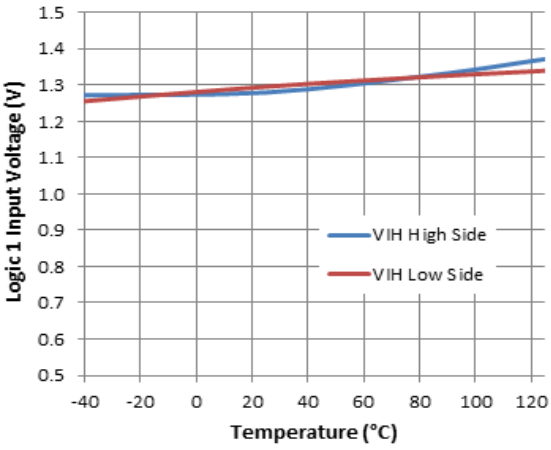


Figure 21. Logic 1 Input Voltage vs. Temperature

Typical Performance Characteristics (continued)

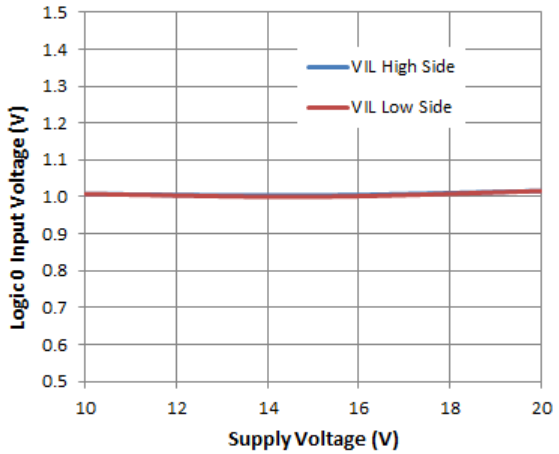


Figure 22. Logic 0 Input Voltage vs. Supply Voltage

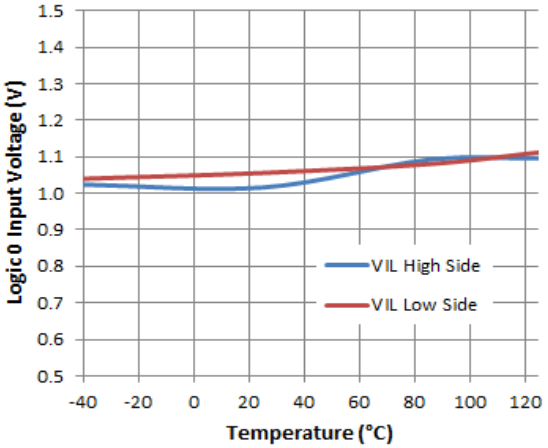


Figure 23. Logic 0 Input Voltage vs. Temperature

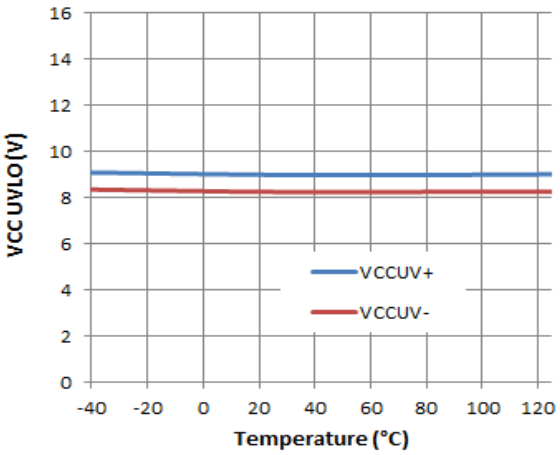


Figure 24. VCC UVLO vs. Temperature

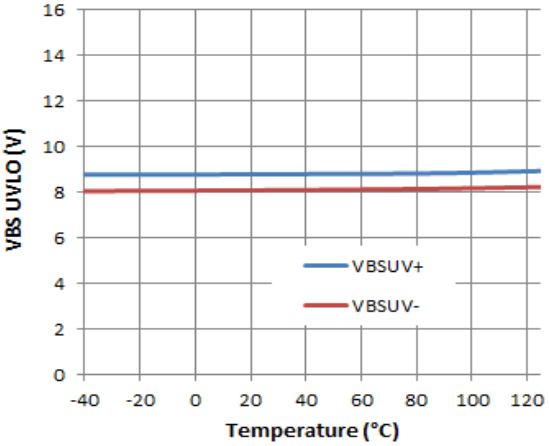


Figure 25. VBS UVLO vs. Temperature

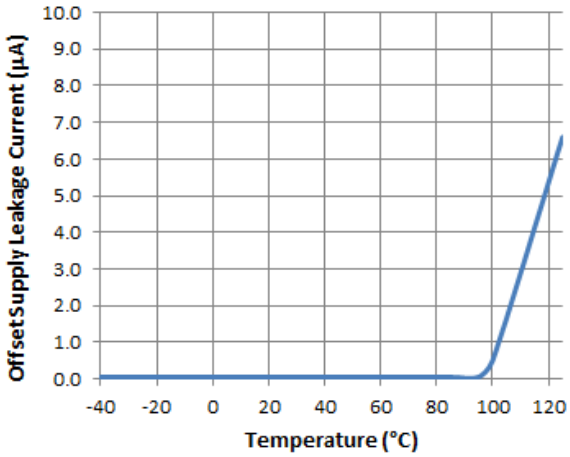
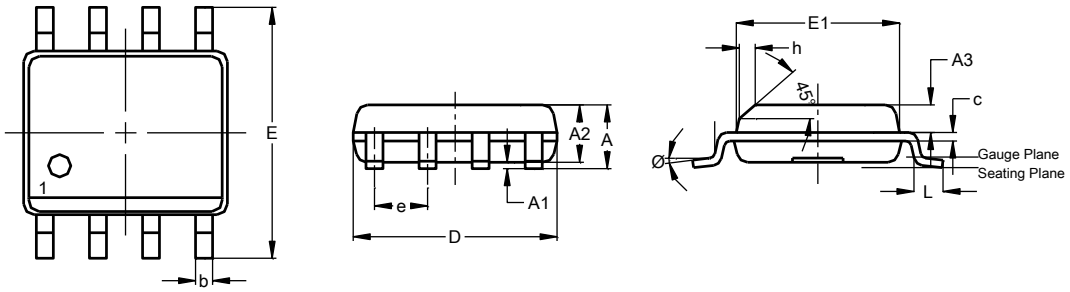


Figure 26. Offset Supply Leakage Current vs. Temperature

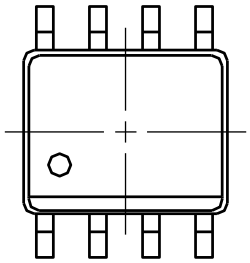
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

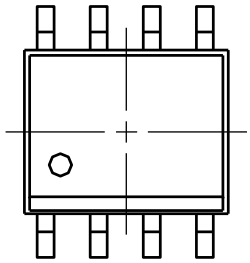
SO-8 (Standard)



SO-8 (Standard)			
Dim	**Min**	**Max**	**Typ**
A	--	1.75	--
A1	0.10	0.25	--
A2	1.25	1.65	--
A3	0.50	0.70	--
b	0.30	0.51	--
c	0.15	0.25	--
D	4.80	5.00	--
E	5.80	6.20	6.00
E1	3.80	4.00	--
e	--	--	1.27
h	0.25	0.50	--
L	0.45	0.82	--
Ø	0°	8°	--
All Dimensions in mm			



OPTION A
(TOP VIEW)



OPTION B
(TOP VIEW)

Suggested Pad Layout

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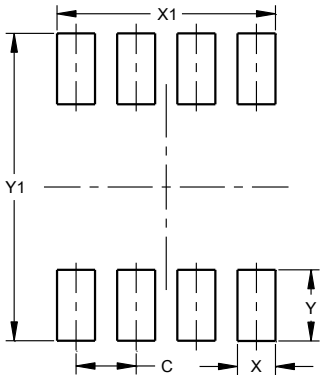
SO-8 (Standard)



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.

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